

IN THE SPECIFICATION:

Please amend paragraph number [0001] as follows:

[0001] This application is a continuation of application Serial No. 09/635,023, filed August 4, 2000, ~~pending,~~ now U.S. Patent 6,326,238, issued December 4, 2001, which is a continuation of application Serial No. 09/210,013 filed December 11, 1998, now U.S. Patent 6,162,662, issued December 19, 2000.

Please amend paragraph number [0008] as follows:

[0008] During semiconductor die attach and wire bonding, the inner leads are typically clamped against a lower heater block or other flat member. The bonding tool itself is configured to compress the wire against the surface to which the wire is being bonded, i.e., a bond pad or inner lead. Examples of such are found in United States Patent 4,600,138 of Hill, United States Patent 4,030,657 of Scheffer, United States Patent 4,603,803 of Chan et al., United States Patent 4,778,097 of Hauser, United States Patent 5,148,959 of Cain et al., United States Patent 5,217,154 of Elwood et al., United States Patent 5,421,503 of Perlberg et al., and United States Patent 5,445,306 of Huddleston. It has generally been found, however, that auxiliary clamping apparatus may improve the quality of “~~second-bonding~~”, bonding,” i.e., bonding of the wire to the inner leads.